IPC ASSOCIATION	Material Com © Copyright 2005. international and P	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				s Materials an	ials and Mfg Information			
uppliei	r Information													
Company name*			Company ur	Company unique ID			Unique ID Authority				Response Date*			
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	Requester Item Number Mfr		Item Number Mfr Item Name				Effective Date Version Manufacturing S		Site	Weight*	UOM	Unit Type		
		NDSH25170A SiC JBS 1700V 2		5A TO247		2024-04-20 CPA			5321.033	mg	Each			
lanufa	acturing Process Information Crid Array N		Terminal Base	Alloy	-STD-020 MSL	Poting	Dook Proces	es Pody Tompor	tura May Tima	at Paul Tomr	Numb	or of Potlow Cv	plac	
	3		CU Allov NA			Kaung	Peak Process Body Temperature Max Time at F		Γ.	k Temperature Number of Reflow Cycles seconds 3				
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RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale app										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die Attach Solder	23.353	mg	Supplier	Silver (Ag)	7440-22-4		0.5838	mg
			A	Lead (Pb)	7439-92-1	7a	21.6015	mg
			Supplier	Tin (Sn)	7440-31-5		1.1677	mg
Die SiC	32.0	mg	Supplier	Silicon Carbide	409-21-2		32	mg
Lead Frame	3488.88	mg	Supplier	Zinc (Zn)	7440-66-6		1.74	mg
			В	Nickel (Ni)	7440-02-0		113.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.09	mg
			Supplier	Copper (Cu)	7440-50-8		3369.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Mold Compound-Black	1739.8	mg		Epoxy resin	proprietary data		104.388	mg
			Supplier	Phenolic Resin	Proprietary Data		104.388	mg
			Supplier	Carbon Black (C)	1333-86-4		8.699	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1478.8301	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		43.495	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg